

ABSTRACT OF THE DISCLOSURE

A package for housing an optoelectronic device such as a photodiode or laser diode is disclosed. The package includes a base having an upper surface. The photodiode chip and related circuitry are mounted to the upper surface of the base. A
5 fiber receptacle structure is mounted to the base and hermetically encloses the photodiode/laser diode chip without the need for a separate cap and lens structure. In the event insulating base is utilized, the plurality of via holes are preferably drilled through the base and the via holes are filled with conductive material thereby enabling the fiber receptacle structure to be hermetically welded to the insulating base using
10 the disclosed process.